Product End-of-Life Disassembly Instructions

Marketing Name/Model	Description
HP Integrity rp8440 Server	Four Cell (16 Socket) Mid-Range Server
Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of this product to remove components and materials requiring selective treatment.	

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

rp8440		
Item Description	Notes	Quantity of items included in product.
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 square cm System backplane (1) PCI backplane (1) PCI OLR board (1) Mass storage backplane (1) Front Panel Display (1) Core I/O (maximum 2) Cell board (maximum 4) PDH riser on cell board (maximum 4) CPU Modules (maximum 16) DIMMs on cell board (maximum 16 per cell board, 64 total) AC Power Distribution board (1) DC Power Distribution board(1) PCI Power Module (maximum 2) Bulk power supply – 2 boards each (maximum 6 supplies, 12 total)	187 (maximum)
	(maximum 76. System backplane, PCI backplane, Cell board)	
Batteries	All types including standard alkaline and lithium coin or button style batteries Cell PDH Riser (1 per cell board, maximum 4). Core IO (1 per core IO card, maximum of 2)	6 (maximum)
Mercury containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 square	Includes background illuminated	

cm		
Cathode Ray Tubes (CRT)		
Capacitors / condensers		
(Containing PCB / PCT)		
Electrolytic Capacitors /	Located in the Bulk Power Supply	Up to 30
Condensers measuring greater	(5 each, maximum of 6 supplies)	
than 2.5 cm in diameter or height		
External electrical cables and		
cords		
Gas Discharge Lamps		
Plastics containing Brominated		
Flame Retardants		
Components and parts containing	Include the cartridges, print	
toner and ink, including liquids,	heads, tubes, vent chambers, and	
semi-liquids (gel/paste) and toner	service stations.	
Components and waste containing		
asbestos		
Components, parts and materials		
containing refractory ceramic fibers		
Components, parts and materials		
containing radioactive substances		

2.0 Tools Required

2.1 List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size
Philips Screw Driver	#2
Flat Head Screw Driver	Small
Flat Head Screw Driver	Large

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1	Battery – locate battery and remove by hand or small flat blade screw driver.
2	Capacitor – locate capacitor and pry from the PCB with a large flat head screw driver.
3	PCB's – follow removal instructions found in the system specific documentation if needed.